



Special Issue on Thin Film Physics and Devices

Call for Papers

Thin films science and technology plays an important role in the high-tech industries. Thin film technology has been developed primarily for the need of the integrated circuit industry. The demand for development of smaller and smaller devices with higher speed especially in new generation of integrated circuits requires advanced materials and new processing techniques suitable for future giga scale integration (GSI) technology. In this regard, physics and technology of thin films can play an important role to achieve this goal. The production of thin films for device purposes has been developed over the past 40 years. Thin films as a two dimensional system are of great importance to many real-world problems. The goal of this special issue is to provide a platform for scientists and academicians all over the world to promote, share, and discuss various new issues and developments in the area of **Thin Film Physics and Devices**.

In this special issue, we invite front-line researchers and authors to submit original research and review articles that explore **Thin Film Physics and Devices**. In this special issue, potential topics include, but are not limited to:

- Thin film material properties
- Thin film technology
- Thin-film photovoltaic cells
- Thin-film batteries
- Thin films in optics
- Magnetic thin film devices
- Thin Film Applications in Advanced Electron Devices

Authors should read over the journal's [Authors' Guidelines](#) carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal's [Paper Submission System](#).

Please kindly specify the “**Special Issue**” under your manuscript title. The research field “**Special Issue - Thin Film Physics and Devices**” should be selected during your submission.

Special Issue timetable:

Submission Deadline	November 27th, 2019
Publication Date	January 2020

Guest Editor:



For further questions or inquiries
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